October 21 (Wed.), 2026

[Oral 08] CMP Consumables (I)

15:10-16:35

International Conference Hall (B1F)

● Session Chair: Xinping Qu (Fudan Univ., China)

15:10-15:35 [Oral 08-1]	**[Invited]** Advanced Ceria Slurries for SiO_2 CMP: Polishing Mechanism of Nanoceria and Emerging Applications Hisataka Minami (Resonac Corp., Japan)
15:35-15:55 ★[Oral 08-2]	W CMP Oxidants for Ultra-low Chemical Dissolution with High Removal Rate Yearin Byun, Thanh Cuong Nguyen, Inkwon Kim, Nohjun Park, Doyoon Kim, Yeonah Jeong, Heechul Moon, and Sangkyun Kim (Samsung Electronics Co., Ltd., Korea)
15:55-16:15 [Oral 08-3]	Advanced Soft Pad Conditioning Solutions for Improved Pad Life and Defectivity in Cu Barrier Applications Uma Rames Krishna Lagudu, Chikai Chiu, Prasoon Gupta, Jiadi Fan (3M, USA), Holden Lee, Chung I Ho, Jason Lin, Yuhsun Wang (3M, Taiwan), Changwan Bea, Yoonghee Na (3M, Korea), Inki Kim (3M, USA), Benson Chen (3M, Taiwan), and Yongsuk Yang (3M, Korea)
16:15-16:35 [Oral 08-4]	CMP Process and Slurries for Memory Device Stacking Yuchun Wang (Anji Microelectronics, China)